



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

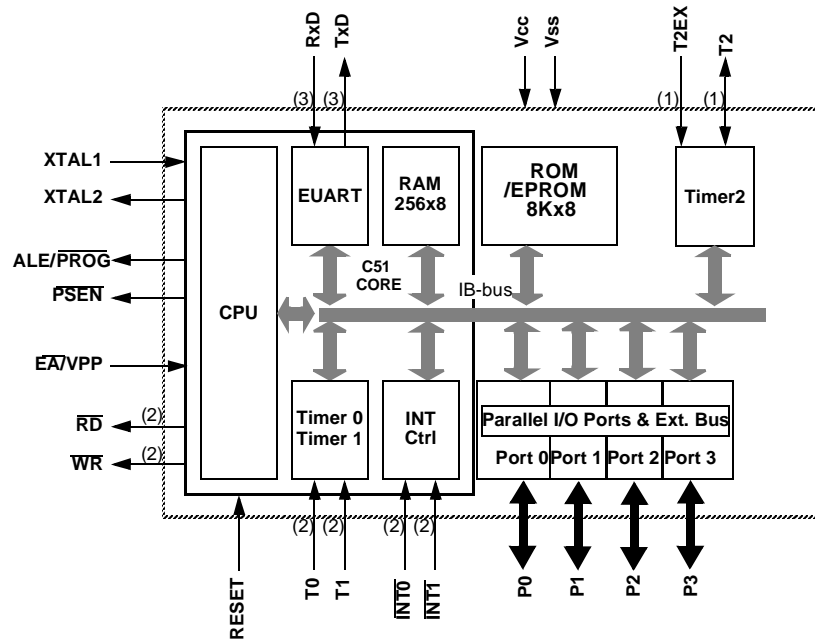
Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c52x2-mib

Table 1. Memory Size

	ROM (bytes)	EPROM (bytes)	TOTAL RAM (bytes)
TS80C32X2	0	0	256
TS80C52X2	8k	0	256
TS87C52X2	0	8k	256

Block Diagram



- Notes: 1. Alternate function of Port 1
2. Alternate function of Port 3

SFR Mapping

The Special Function Registers (SFRs) of the TS80C52X2 fall into the following categories:

- C51 core registers: ACC, B, DPH, DPL, PSW, SP, AUXR1
- I/O port registers: P0, P1, P2, P3
- Timer registers: T2CON, T2MOD, TCON, TH0, TH1, TH2, TMOD, TL0, TL1, TL2, RCAP2L, RCAP2H
- Serial I/O port registers: SADDR, SADEN, SBUF, SCON
- Power and clock control registers: PCON
- Interrupt system registers: IE, IP, IPH
- Others: AUXR, CKCON

Timer 2

The timer 2 in the TS80C52X2 is compatible with the timer 2 in the 80C52.

It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 5) and T2MOD register (See Table 6). Timer 2 operation is similar to Timer 0 and Timer 1. C/T2 selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/RL2 (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.

Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C52X2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

Auto-reload Mode

The Auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 4. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.

1111 0000b).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
SADDR 0101 0110b
SADEN 1111 1100b
Broadcast =SADDR OR SADEN1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b
      SADEN1111 1010b
Broadcast1111 1X11b,
```

```
Slave B:SADDR1111 0011b
      SADEN1111 1001b
Broadcast1111 1X11b,
```

```
Slave C:SADDR=1111 0010b
      SADEN1111 1101b
Broadcast1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send an address FBh.

Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Table 7. SADEN Register
SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

Table 8. SADDR Register
SADDR - Slave Address Register (A9h)

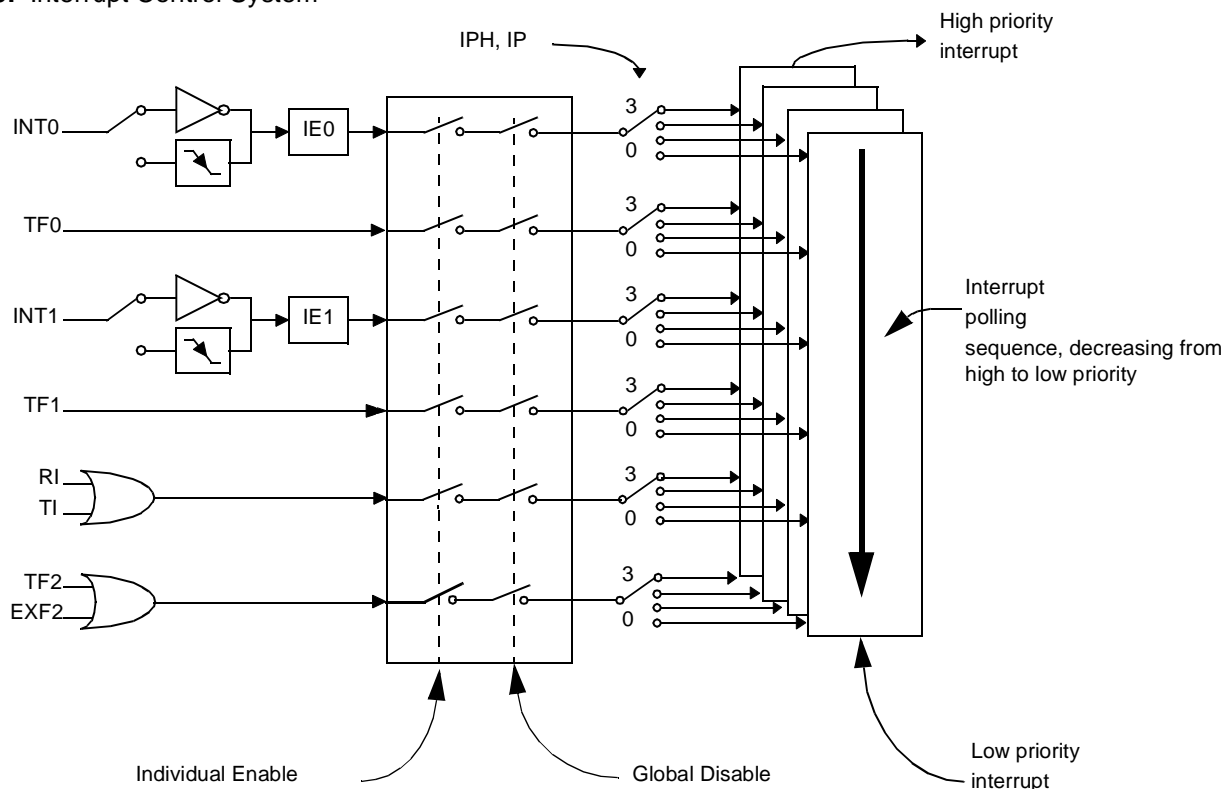
7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

Interrupt System

The TS80C52X2 has a total of 6 interrupt vectors: two external interrupts ($\overline{\text{INT0}}$ and $\overline{\text{INT1}}$), three timer interrupts (timers 0, 1 and 2) and the serial port interrupt. These interrupts are shown in Figure 9.

Figure 9. Interrupt Control System



Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 12.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 13.) and in the Interrupt Priority High register (See Table 14.). shows the bit values and priority levels associated with each combination.

Table 11. Priority Level Bit Values

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level

Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occurred during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

Power-down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 10., PCON register).

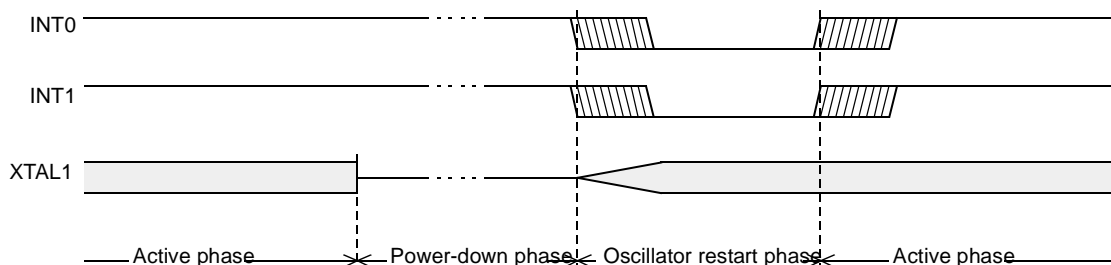
In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 10. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C52X2 into power-down mode.

Figure 10. Power-down Exit Waveform



Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does not affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

Note: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Table 15. The State of Ports During Idle and Power-down Modes

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data ⁽¹⁾	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data ⁽¹⁾	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

Note: 1. Port 0 can force a "zero" level. A "one" will leave port floating.

Reduced EMI Mode

The ALE signal is used to demultiplex address and data buses on port 0 when used with external program or data memory. Nevertheless, during internal code execution, ALE signal is still generated. In order to reduce EMI, ALE signal can be disabled by setting AO bit.

The AO bit is located in AUXR register at bit location 0. As soon as AO is set, ALE is no longer output but remains active during MOVX and MOVC instructions and external fetches. During ALE disabling, ALE pin is weakly pulled high.

Table 18. AUXR Register
AUXR - Auxiliary Register (8Eh)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	AO

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
0	AO	ALE Output bit Clear to restore ALE operation during internal fetches. Set to disable ALE operation during internal fetches.

Reset Value = XXXX XXX0b
Not bit addressable

TS80C52X2

ROM Structure

The TS80C52X2 ROM memory is divided in three different arrays:

- the code array:8 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The lock bits when programmed according to Table 19. will provide different level of protection for the on-chip code and data.

Table 19. Program Lock bits

Program Lock Bits				Protection Description
Security level	LB1	LB2	LB3	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset.

U: unprogrammed

P: programmed

Signature bytes

The TS80C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

Verify Algorithm

Refer to Section "Verify Algorithm".

Programming Algorithm

The Improved Quick Pulse algorithm is based on the Quick Pulse algorithm and decreases the number of pulses applied during byte programming from 25 to 1.

To program the TS87C52X2 the following sequence must be exercised:

- Step 1: Activate the combination of control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Input the appropriate data on the data lines.
- Step 4: Raise \overline{EA}/VPP from VCC to VPP (typical 12.75V).
- Step 5: Pulse ALE/ \overline{PROG} once.
- Step 6: Lower \overline{EA}/VPP from VPP to VCC

Repeat step 2 through 6 changing the address and data for the entire array or until the end of the object file is reached (See Figure 12.).

Verify Algorithm

Code array verify must be done after each byte or block of bytes is programmed. In either case, a complete verify of the programmed array will ensure reliable programming of the TS87C52X2.

P 2.7 is used to enable data output.

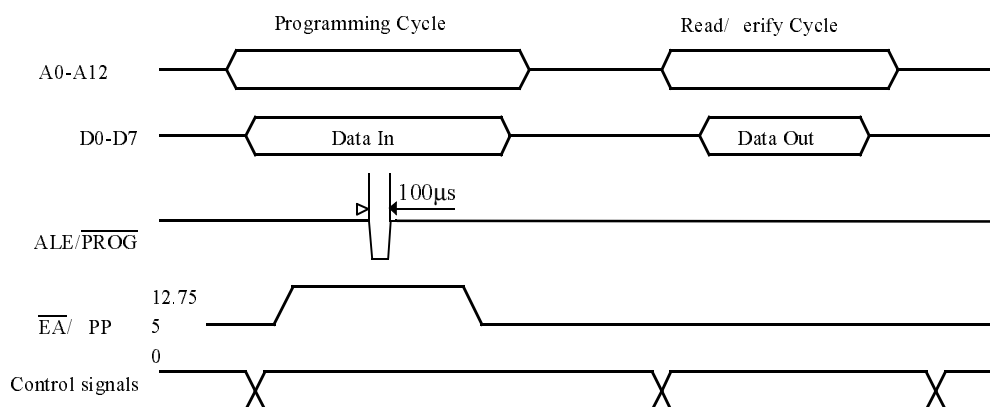
To verify the TS87C52X2 code the following sequence must be exercised:

- Step 1: Activate the combination of program and control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Read data on the data lines.

Repeat step 2 through 3 changing the address for the entire array verification (See Figure 12.).

The encryption array cannot be directly verified. Verification of the encryption array is done by observing that the code array is well encrypted.

Figure 12. Programming and Verification Signal's Waveform



EPROM Erasure (Windowed Packages Only)

Erasing the EPROM erases the code array, the encryption array and the lock bits returning the parts to full functionality.

Erasure leaves all the EPROM cells in a 1's state (FF).

Erasure Characteristics

The recommended erasure procedure is exposure to ultraviolet light (at 2537 Å) to an integrated dose at least 15 W-sec/cm². Exposing the EPROM to an ultraviolet lamp of

12,000 $\mu\text{W}/\text{cm}^2$ rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.

Signature Bytes

The TS80/87C52X2 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 31. for Read Signature Bytes. Table 35. shows the content of the signature byte for the TS80/87C52X2.

Table 21. Signature Bytes Content

Location	Contents	Comment
30h	58h	Manufacturer Code: Atmel
31h	57h	Family Code: C51 X2
60h	2Dh	Product name: TS80C52X2
60h	ADh	Product name: TS87C52X2
60h	20h	Product name: TS80C32X2
61h	FFh	Product revision number

Electrical Characteristics

Absolute Maximum Ratings⁽¹⁾

Ambient Temperature Under Bias:

C = commercial.....	0°C to 70°C
I = industrial	-40°C to 85°C
Storage Temperature	-65°C to + 150°C
Voltage on V _{CC} to V _{SS}	-0.5V to + 7 V
Voltage on V _{PP} to V _{SS}	-0.5V to + 13 V
Voltage on Any Pin to V _{SS}	-0.5V to V _{CC} + 0.5V
Power Dissipation	1 W ⁽²⁾

- Notes:
1. Stresses at or above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
 2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating I_{cc} measurements under reset, which made sense for the designs where the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating I_{cc}:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = V_{CC}, RST = V_{SS}, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating I_{cc}.

DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾
V _{OL1}	Output Low Voltage, port 0 ⁽⁶⁾			0.3	V	I _{OL} = 200 μA ⁽⁴⁾
				0.45	V	I _{OL} = 3.2 mA ⁽⁴⁾
				1.0	V	I _{OL} = 7.0 mA ⁽⁴⁾
V _{OL2}	Output Low Voltage, ALE, $\overline{\text{PSEN}}$			0.3	V	I _{OL} = 100 μA ⁽⁴⁾
				0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾

Table 22. DC Parameters in Standard Voltage (Continued)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{OH}	Output High Voltage, ports 1, 2, 3	$V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$			V V V	$I_{OH} = -10 \mu A$ $I_{OH} = -30 \mu A$ $I_{OH} = -60 \mu A$ $V_{CC} = 5V \pm 10\%$
V_{OH1}	Output High Voltage, port 0	$V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$			V V V	$I_{OH} = -200 \mu A$ $I_{OH} = -3.2 mA$ $I_{OH} = -7.0 mA$ $V_{CC} = 5V \pm 10\%$
V_{OH2}	Output High Voltage, ALE, \overline{PSEN}	$V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$			V V V	$I_{OH} = -100 \mu A$ $I_{OH} = -1.6 mA$ $I_{OH} = -3.5 mA$ $V_{CC} = 5V \pm 10\%$
R_{RST}	RST Pulldown Resistor	50	90 ⁽⁵⁾	200	k Ω	
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	μA	$V_{in} = 0.45V$
I_{LI}	Input Leakage Current			± 10	μA	$0.45V < V_{in} < V_{CC}$
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	μA	$V_{in} = 2.0 V$
C_{IO}	Capacitance of I/O Buffer			10	pF	$F_c = 1 MHz$ $T_A = 25^\circ C$
I_{PD}	Power Down Current		20 ⁽⁵⁾	50	μA	$2.0 V < V_{CC} < 5.5V^{(3)}$
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			1 + 0.4 Freq (MHz) at 12MHz 5.8 at 16MHz 7.4	mA	$V_{CC} = 5.5V^{(1)}$
I_{CC} operating	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			3 + 0.6 Freq (MHz) at 12MHz 10.2 at 16MHz 12.6	mA	$V_{CC} = 5.5V^{(8)}$
I_{CC} idle	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			0.25+0.3 Freq (MHz) at 12MHz 3.9 at 16MHz 5.1	mA	$V_{CC} = 5.5V^{(2)}$

Port 0: 26 mA

Ports 1, 2 and 3: 15 mA

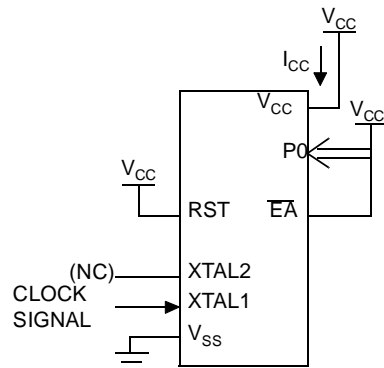
Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

7. For other values, please contact your sales office.

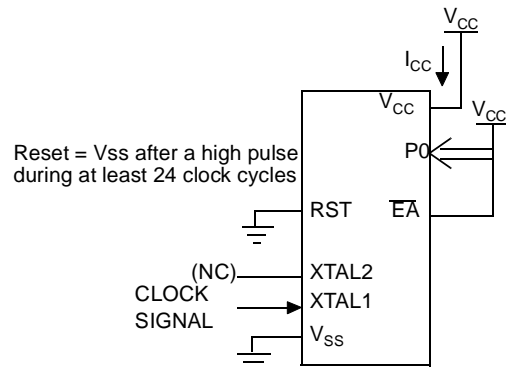
8. Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns (see Figure 17.), $V_{IL} = V_{SS} + 0.5V$, $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C.; $\overline{EA} = \text{Port 0} = V_{CC}$; RST = V_{SS} . The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.

Figure 13. I_{CC} Test Condition, under reset



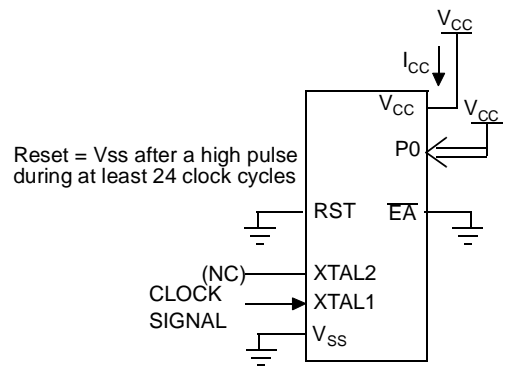
All other pins are disconnected.

Figure 14. Operating I_{CC} Test Condition



All other pins are disconnected.

Figure 15. I_{CC} Test Condition, Idle Mode



All other pins are disconnected.

Figure 16. I_{CC} Test Condition, Power-down Mode

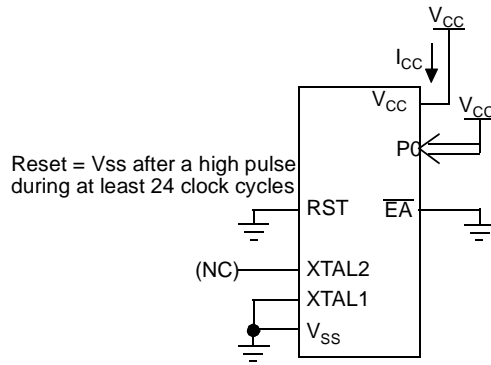
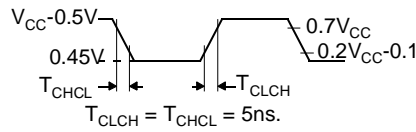


Figure 17. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes



AC Parameters

Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a “T” (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{AVLL} = Time for Address Valid to ALE Low.

T_{LLPL} = Time for ALE Low to PSEN Low.

$T_A = 0$ to $+70^{\circ}C$ (commercial temperature range); $V_{SS} = 0V$; $V_{CC} = 5V \pm 10\%$; -M and -V ranges.

$T_A = -40^{\circ}C$ to $+85^{\circ}C$ (industrial temperature range); $V_{SS} = 0V$; $V_{CC} = 5V \pm 10\%$; -M and -V ranges.

$T_A = 0$ to $+70^{\circ}C$ (commercial temperature range); $V_{SS} = 0V$; $2.7V < V_{CC} < 5.5V$; -L range.

$T_A = -40^{\circ}C$ to $+85^{\circ}C$ (industrial temperature range); $V_{SS} = 0V$; $2.7V < V_{CC} < 5.5V$; -L range.

Table 24. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and PSEN signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 24. Load Capacitance versus speed range, in pF

	-M	-V	-L
Port 0	100	50	100
Port 1, 2, 3	80	50	80
ALE / PSEN	100	30	100

Table 5., Table 29. and Table 32. give the description of each AC symbols.

Table 27., Table 30. and Table 33. give for each range the AC parameter.

Table 28., Table 31. and Table 34. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 25. Max frequency for derating formula regarding the speed grade

	-M X1 mode	-M X2 mode	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

Example:

T_{LLIV} in X2 mode for a -V part at 20 MHz ($T = 1/20^{E6} = 50$ ns):

$x = 22$ (Table 28.)

$T = 50$ ns

$T_{LLIV} = 2T - x = 2 \times 50 - 22 = 78$ ns

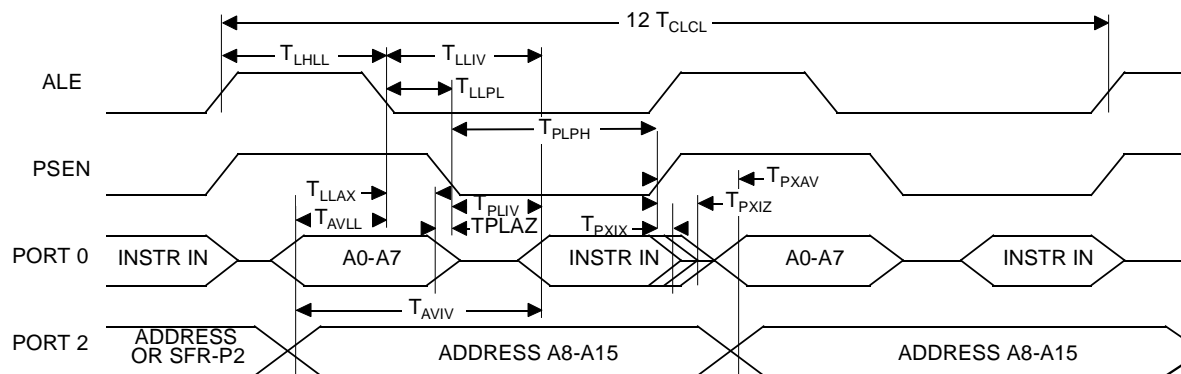
External Program Memory Characteristics

Table 26. Symbol Description

Symbol	Parameter
T	Oscillator clock period
T_{LHLL}	ALE pulse width
T_{AVLL}	Address Valid to ALE
T_{LLAX}	Address Hold After ALE
T_{LLIV}	ALE to Valid Instruction In
T_{LLPL}	ALE to \overline{PSEN}
T_{PLPH}	\overline{PSEN} Pulse Width
T_{PLIV}	\overline{PSEN} to Valid Instruction In
T_{PXIX}	Input Instruction Hold After \overline{PSEN}
T_{PXIZ}	Input Instruction Float After \overline{PSEN}
T_{PXAV}	\overline{PSEN} to Address Valid
T_{AVIV}	Address to Valid Instruction In
T_{PLAZ}	\overline{PSEN} Low to Address Float

External Program Memory Read Cycle

Figure 18. External Program Memory Read Cycle



External Data Memory Characteristics

Table 29. Symbol Description

Symbol	Parameter
T_{RLRH}	\overline{RD} Pulse Width
T_{WLWH}	\overline{WR} Pulse Width
T_{RLDV}	\overline{RD} to Valid Data In
T_{RHDZ}	Data Hold After \overline{RD}
T_{RHDZ}	Data Float After \overline{RD}
T_{LLDV}	ALE to Valid Data In
T_{AVDV}	Address to Valid Data In
T_{LLWL}	ALE to \overline{WR} or \overline{RD}
T_{AVWL}	Address to \overline{WR} or \overline{RD}
T_{QVWX}	Data Valid to \overline{WR} Transition
T_{QVWH}	Data set-up to \overline{WR} High
T_{WHQX}	Data Hold After \overline{WR}
T_{RLAZ}	\overline{RD} Low to Address Float
T_{WHLH}	\overline{RD} or \overline{WR} High to ALE high

Table 30. AC Parameters for a Fix Clock

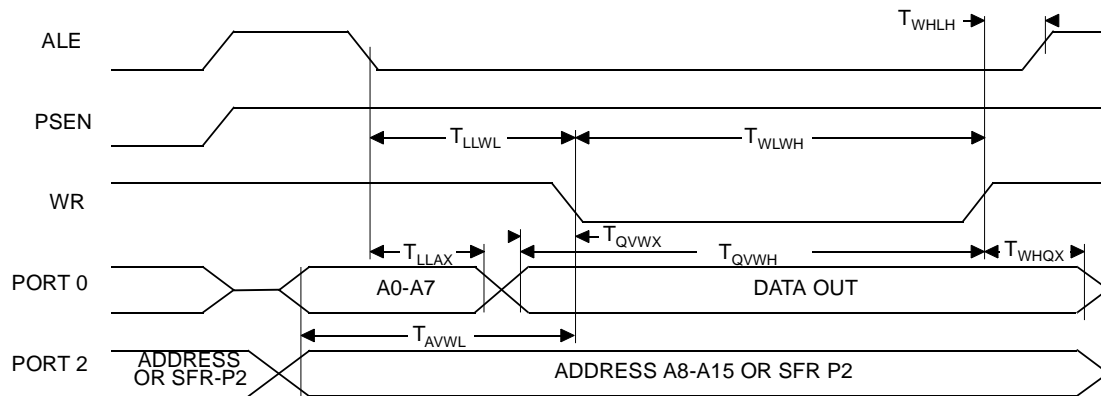
Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDV}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Table 31. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	$6 T - x$	$3 T - x$	20	15	25	ns
T_{WLWH}	Min	$6 T - x$	$3 T - x$	20	15	25	ns
T_{RLDV}	Max	$5 T - x$	$2.5 T - x$	25	23	30	ns
T_{RHDX}	Min	x	x	0	0	0	ns
T_{RHDZ}	Max	$2 T - x$	$T - x$	20	15	25	ns
T_{LLDV}	Max	$8 T - x$	$4 T - x$	40	35	45	ns
T_{AVDV}	Max	$9 T - x$	$4.5 T - x$	60	50	65	ns
T_{LLWL}	Min	$3 T - x$	$1.5 T - x$	25	20	30	ns
T_{LLWL}	Max	$3 T + x$	$1.5 T + x$	25	20	30	ns
T_{AVWL}	Min	$4 T - x$	$2 T - x$	25	20	30	ns
T_{QVWX}	Min	$T - x$	$0.5 T - x$	15	10	20	ns
T_{QVWH}	Min	$7 T - x$	$3.5 T - x$	15	10	20	ns
T_{WHQX}	Min	$T - x$	$0.5 T - x$	10	8	15	ns
T_{RLAZ}	Max	x	x	0	0	0	ns
T_{WHLH}	Min	$T - x$	$0.5 T - x$	15	10	20	ns
T_{WHLH}	Max	$T + x$	$0.5 T + x$	15	10	20	ns

External Data Memory Write Cycle

Figure 19. External Data Memory Write Cycle



EPROM Programming and Verification Characteristics

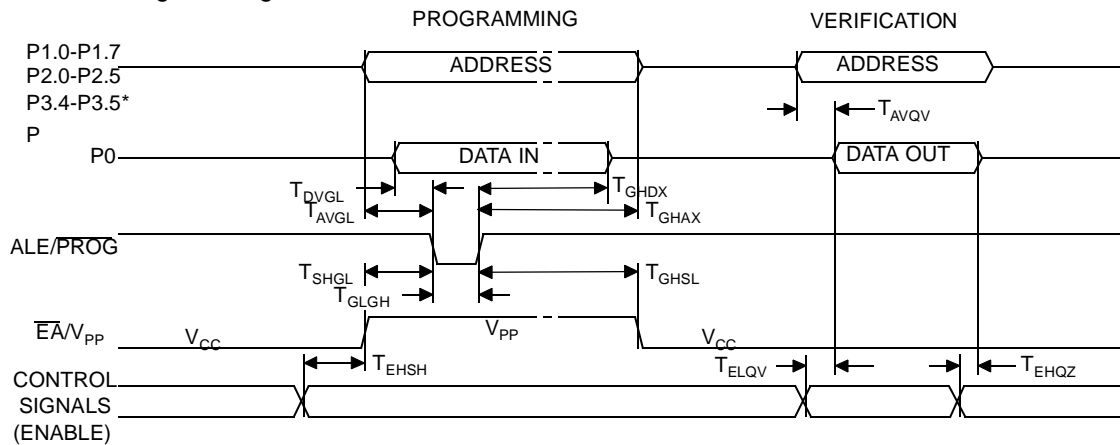
$T_A = 21^{\circ}\text{C}$ to 27°C ; $V_{SS} = 0\text{V}$; $V_{CC} = 5\text{V} \pm 10\%$ while programming. V_{CC} = operating range while verifying.

Table 35. EPROM Programming Parameters

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	12.5	13	V
I_{PP}	Programming Supply Current		75	mA
$1/T_{CLCL}$	Oscillator Frequency	4	6	MHz
T_{AVGL}	Address Setup to $\overline{\text{PROG}}$ Low	$48 T_{CLCL}$		
T_{GHAX}	Address Hold after $\overline{\text{PROG}}$	$48 T_{CLCL}$		
T_{DVGL}	Data Setup to $\overline{\text{PROG}}$ Low	$48 T_{CLCL}$		
T_{GHDX}	Data Hold after $\overline{\text{PROG}}$	$48 T_{CLCL}$		
T_{EHS}	(Enable) High to V_{PP}	$48 T_{CLCL}$		
T_{SHGL}	V_{PP} Setup to $\overline{\text{PROG}}$ Low	10		μs
T_{GHSL}	V_{PP} Hold after $\overline{\text{PROG}}$	10		μs
T_{GLGH}	$\overline{\text{PROG}}$ Width	90	110	μs
T_{AVQV}	Address to Valid Data		$48 T_{CLCL}$	
T_{ELQV}	ENABLE Low to Data Valid		$48 T_{CLCL}$	
T_{EHQZ}	Data Float after ENABLE	0	$48 T_{CLCL}$	

EPROM Programming and Verification Waveforms

Figure 22. EPROM Programming and Verification Waveforms



* 8KB: up to P2.4, 16KB: up to P2.5, 32KB: up to P3.4, 64KB: up to P3.5